



## **Avago Technologies To Present At Lehman Brothers High Yield Bond And Syndicated Loan Conference**

March 5, 2008

San Jose, Calif., March 5, 2008

Avago Technologies, a leading supplier of analog interface components for communications, industrial and consumer applications, today announced Avago management will participate in the Lehman Brothers 2008 High Yield Bond and Syndicated Loan Conference in Orlando, Fla., on Thursday, March 13, 2008 at 9:30 a.m. ET.

Event: Lehman Brothers 2008 High Yield Bond and Syndicated Loan Conference

Date: Thursday, March 13, 2008

Presentation Time: 9:30 a.m. ET

Location: Disney Yacht and Beach Club – Orlando, Fla.

Webcast: [http://www.avagotech.com/investor\\_comms/](http://www.avagotech.com/investor_comms/)

### **About Avago Technologies**

Avago Technologies is a leading supplier of analog interface components for communications, industrial and consumer applications. By leveraging its core competencies in III-V compound and silicon semiconductor design and processing, the company provides an extensive range of analog, mixed signal and optoelectronics components and subsystems to more than 40,000 customers. Backed by strong customer service support, the company's products serve four diverse end markets: industrial and automotive, wired infrastructure, wireless communications, and computer peripherals. Avago has a global employee presence and heritage of technical innovation dating back 40 years to its Hewlett-Packard roots. Information about Avago is available on the Web at [www.avagotech.com](http://www.avagotech.com).

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### **Press Contact**

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